HD74HC00

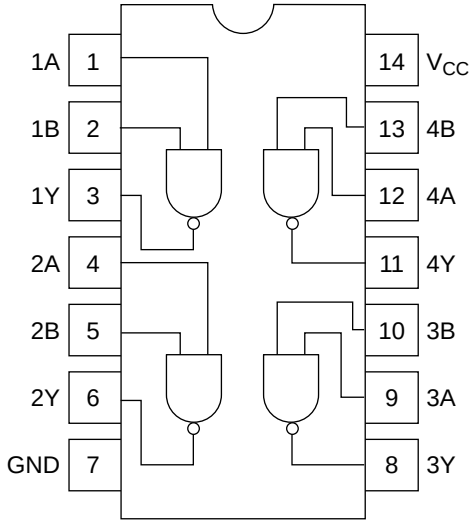
Quad. 2-input NAND Gates

HITACHI

Features

- High Speed Operation: t_{pd} = 8.5 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: V_{CC} = 2 to 6 V
- Low Input Current: 1 µA max
- Low Quiescent Supply Current: I_{CC} (static) = 1 µA max (Ta = 25°C)

Pin Arrangement



(Top view)

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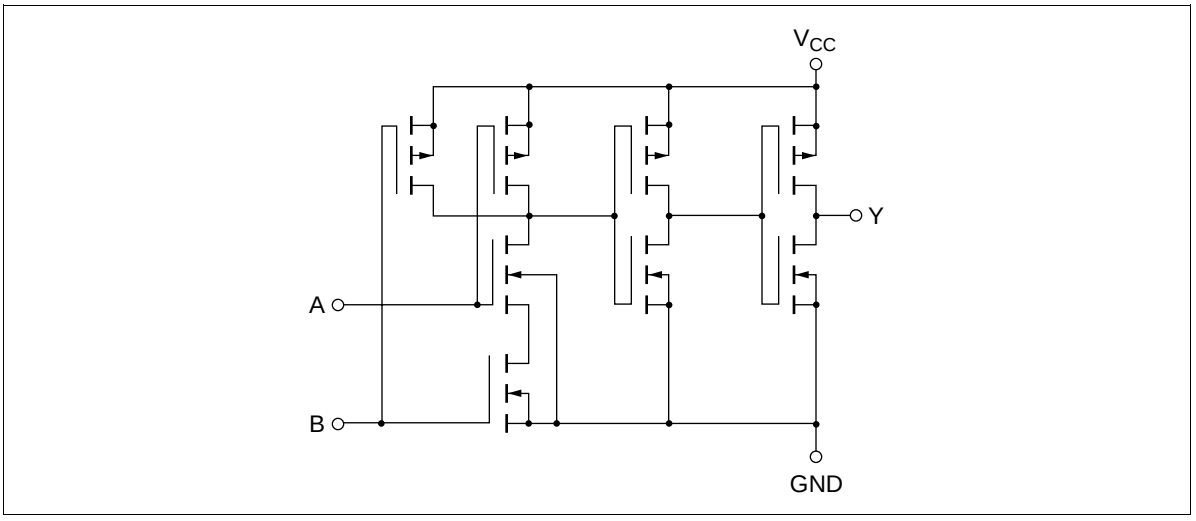
Circuit Schematic (1/4)



DC Characteristics

Item	Symbol	V_{cc} (V)	Ta = 25°C Min	Typ	Max	Ta = –40 to +85°C Min	Max	Unit	Test Conditions	
Input voltage	V_{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V_{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V_{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V_{IH} or V_{IL}	I_{OH} = –20 µA
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I_{OH} = –4 mA
		6.0	5.68	—	—	5.63	—			I_{OH} = –5.2 mA
	V_{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V_{IH} or V_{IL}	I_{OL} = 20 µA
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I_{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I_{OL} = 5.2 mA

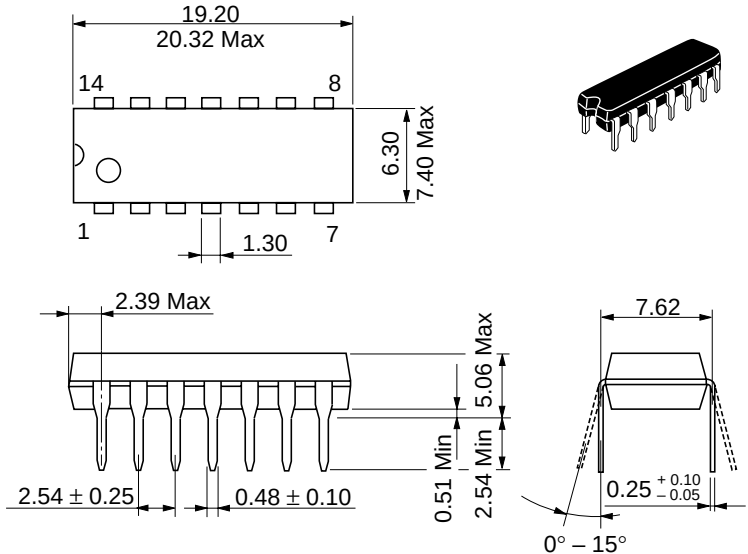
DC Characteristics (cont)

Item	Symbol	V_{CC} (V)	Ta = 25°C Min	Typ	Max	Ta = –40 to +85°C Min	Max	Unit	Test Conditions
Input current	Iin	6.0	—	—	±0.1	—	±1.0	µA	Vin = V_{CC} or GND
Quiescent supply current	I_{CC}	6.0	—	—	1.0	—	10	µA	Vin = V_{CC} or GND, Iout = 0 µA

AC Characteristics (C_L = 50 pF, Input $t_r = t_f$ = 6 ns)

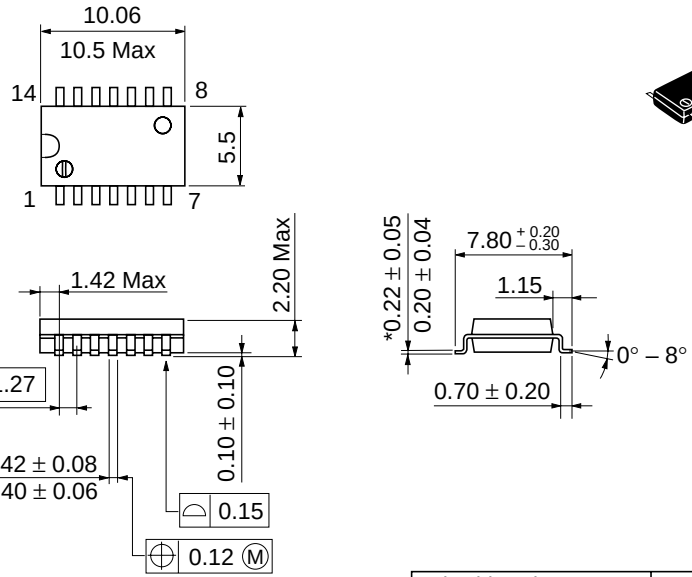
Item	Symbol	V_{CC} (V)	Ta = 25°C Min	Typ	Max	Ta = –40 to +85°C Min	Max	Unit	Test Conditions
Propagation delay time	t_{PLH}	2.0	—	—	90	—	115	ns	
		4.5	—	9	18	—	23		
		6.0	—	—	15	—	20		
	t_{PHL}	2.0	—	—	90	—	115	ns	
		4.5	—	8	18	—	23		
		6.0	—	—	15	—	20		
Output rise time	t_{TLH}	2.0	—	—	75	—	95	ns	
		4.5	—	7	15	—	19		
		6.0	—	—	13	—	16		
Output fall time	t_{THL}	2.0	—	—	75	—	95	ns	
		4.5	—	7	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	Cin	—	—	5	10	—	10	pF	

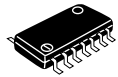
Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm

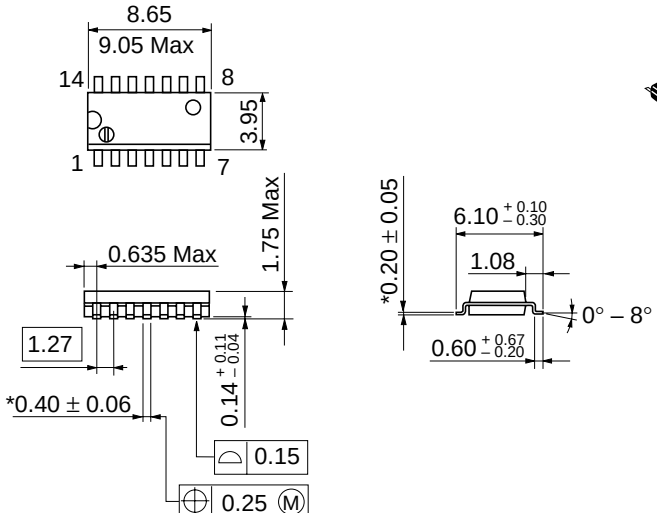




Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g

*Dimension including the plating thickness
Base material dimension

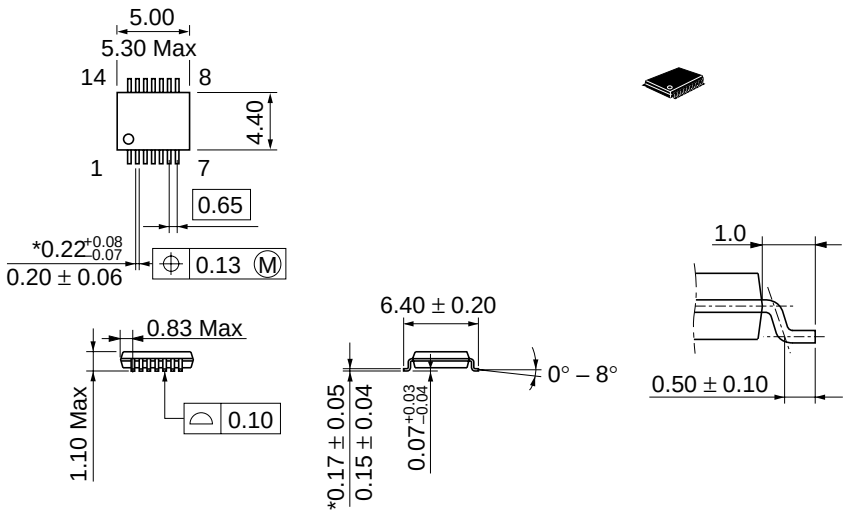
Unit: mm



Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

*Pd plating

Unit: mm



Hitachi Code	TTP-14D
JEDEC	—
EIAJ	—
Weight (reference value)	0.05 g

*Dimension including the plating thickness
Base material dimension

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